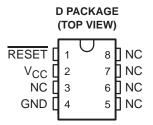
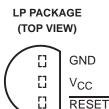
- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Low Standby Current . . . 20 μA
- RESET Output Defined When V<sub>CC</sub> Exceeds 1 V
- Precision Threshold Voltage 4.55 V ±120 mV
- High Output Sink Capability . . . 20 mA
- Comparator Hysteresis Prevents Erratic Resets

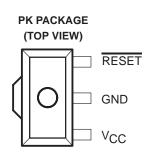
#### description/ordering information

The TL7757 is a supply-voltage supervisor designed for use in microcomputer and microprocessor systems. The supervisor monitors the supply voltage for undervoltage conditions. During power up, when the supply voltage,  $V_{CC}$ , attains a value approaching 1 V, the RESET output becomes active (low) to prevent undefined operation. If the supply voltage drops below threshold voltage level ( $V_{IT-}$ ), the RESET output goes to the active (low) level until the supply undervoltage fault condition is eliminated.









GND is in electrical contact with the tab.

TA	PACKAG	Eţ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC (D)	Tube of 75	TL7757CD	7757C
	3010 (D)	Reel of 2500	TL7757CDR	11510
0°C to 70°C	SOT (PK)	Reel of 1000	TL7757CPK	T7
	TO226 / TO-92 (LP)	Bulk of 1000	TL7757CLP	TL7757C
	10220710-92 (LP)	Reel of 2000	TL7757CLPR	12/75/0
	SOIC (D)	Tube of 75	TL7757ID	77571
	3010 (D)	Reel of 2500	TL7757IDR	77571
–40°C to 85°C	SOT (PK)	Reel of 1000	TL7757IPK	71
	TO226 / TO-92 (LP)	Bulk of 1000	of 1000 TL7757ILP	
	102207 10 02 (EF)	Reel of 2000	TL7757ILPR	TL7757I

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

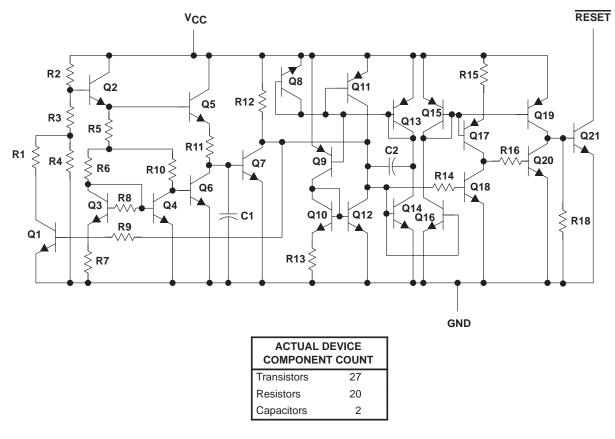


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# TL7757 SUPPLY-VOLTAGE SUPERVISOR AND PRECISION VOLTAGE DETECTOR

SLVS041I – SEPTEMBER 1991 – REVISED AUGUST 2003

#### equivalent schematic



### absolute maximum ratings over operating junction temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> (see Note 1)		–0.3 V to 20 V
Off-state output voltage range (see Note 1)		–0.3 V to 20 V
Output current, I <sub>O</sub>		30 mA
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3):	: D package	97°C/W
	LP package	140°C/W
	PK package	52°C/W
Operating virtual junction temperature, T <sub>J</sub>		150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10	seconds	260°C
Storage temperature range, T <sub>stg</sub>		-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network terminal ground.

- 2. Maximum power dissipation is a function of T<sub>.I</sub>(max),  $\theta_{.IA}$ , and T<sub>A</sub>. The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



#### recommended operating conditions

			MIN	MAX	UNIT
VCC	Supply voltage		1	7	V
VOH	High-level output voltage			15	V
IOL	Low-level output current			20	mA
т.	Operating free-air temperature		0	70	°C
TA			-40	85	C

#### electrical characteristics at specified free-air temperature

	PARAMETER	TEST CONDITIONS	т.	TL7757C			
	PARAMETER	TEST CONDITIONS	TA	MIN	TYP	MAX	UNIT
	Negative-going input threshold voltage at $V_{CC}$		25°C	4.43	4.55	4.67	V
VIT-	Negative-going input threshold voltage at VCC		0°C to 70°C	4.4		4.7	V
· +	Hysteresis at $V_{CC}$		25°C	40	50	60	mV
V <sub>hys</sub> †			0°C to 70°C	30		70	IIIV
Ve	Low-level output voltage	I <sub>OL</sub> = 20 mA, V <sub>CC</sub> = 4.3 V	25°C		0.4	0.8	V
VOL		OL = 20  MA,  VCC = 4.3  V	0°C to 70°C			0.8	v
	High-level output current	$V_{CC} = 7 \text{ V}, \qquad V_{OH} = 15 \text{ V},$ See Figure 1	25°C			1	μA
ЮН			0°C to 70°C			1	μΑ
v t	Power-up reset voltage	RL = 2.2 kΩ,	25°C		0.8	1	V
V <sub>res</sub> ‡	Power-up reser voltage	$V_{CC}$ slew rate $\leq 5 V/\mu s$	0°C to 70°C			1.2	V
		V <sub>CC</sub> = 4.3 V	25°C		1400	2000	
ICC	Supply current	VCC = 4.3 V	0°C to 70°C			2000	μA
		V <sub>CC</sub> = 5.5 V	0°C to 70°C			40	

<sup>†</sup> This is the difference between positive-going input threshold voltage, V<sub>IT+</sub>, and negative-going input threshold voltage, V<sub>IT-</sub>. <sup>‡</sup> This is the lowest voltage at which RESET becomes active.

### switching characteristics at specified free-air temperature

PARAMETER		TEST CONDITIONS	T	TL7757C				
	PARAMETER	TEST CONDITIONS	Τ <sub>Α</sub>	MIN	TYP	MAX	UNIT	
Propagation delay time, low-to-high-level V <sub>CC</sub> slew r		$V_{CC}$ slew rate $\leq 5 V/\mu s$ ,	25°C		3.4	5	μs	
<sup>t</sup> PLH	output	See Figures 2 and 3	0°C to 70°C			5	μs	
1	Propagation delay time, high-to-low-level	See Figures 2 and 3	25°C		2	5		
<sup>t</sup> PHL	output	See Figures 2 and 5	0°C to 70°C			5	μs	
	Rise time	$V_{CC}$ slew rate $\leq 5 \text{ V/}\mu\text{s}$ , See Figures 2 and 3	25°C		0.4	1		
t <sub>r</sub>	Rise time		0°C to 70°C			1	μs	
+.		Fall time See Figures 2 and 3	See Figures 2 and 3	25°C		0.05	1	
tf	Fairune	See Figures 2 and 5	0°C to 70°C			1	μs	
+	Minimum pulse duration at $V_{CC}$ for output		25°C			5		
<sup>t</sup> w(min)	response		0°C to 70°C			5	μs	



#### electrical characteristics at specified free-air temperature

	PARAMETER	TEST CONDITIONS	т.	TL7757I			
	PARAMETER	TEST CONDITIONS	TA	MIN	TYP	MAX	UNIT
V	Negative-going input threshold voltage at VCC		25°C	4.43	4.55	4.67	v
VIT-	Negative-going input threshold voltage at VCC		–40°C to 85°C	4.4		4.7	v
· +	Hystorosis at Vac		25°C	40	50	60	mV
V <sub>hys</sub> †	Hysteresis at V <sub>CC</sub>		–40°C to 85°C	30		70	ΠV
	Low-level output voltage	I <sub>OL</sub> = 20 mA, V <sub>CC</sub> = 4.3 V	25°C		0.4	0.8	V
VOL			–40°C to 85°C			0.8	
lau	High-level output current	$V_{CC} = 7 V$ , $V_{OH} = 15 V$ , See Figure 1	25°C			1	
ЮН			–40°C to 85°C			1	μA
v +		$R_{I} = 2.2 \text{ k}\Omega_{2}$	25°C		0.8	1	V
V <sub>res</sub> ‡	Power-up reset voltage	V <sub>CC</sub> slew rate ≤ 5 V/µs	–40°C to 85°C			1.2	v
			25°C		1400	2000	
ICC	Supply current	V <sub>CC</sub> = 4.3 V	–40°C to 85°C			2100	μA
		V <sub>CC</sub> = 5.5 V	–40°C to 85°C			40	

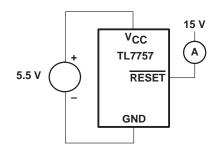
<sup>†</sup> This is the difference between positive-going input threshold voltage, V<sub>IT+</sub>, and negative-going input threshold voltage, V<sub>IT-</sub>. <sup>‡</sup>This is the lowest voltage at which RESET becomes active.

#### switching characteristics at specified free-air temperature

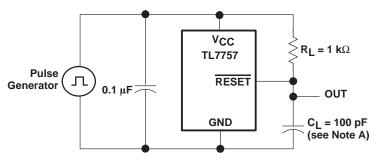
	PARAMETER	TEST CONDITIONS		TL7757I			
	PARAMETER	TEST CONDITIONS	TA	MIN	TYP	MAX	UNIT
touu	Propagation delay time, low-to-high-level output	$V_{CC}$ slew rate $\leq 5 V/\mu s$ ,	25°C		3.4	5	μs
<sup>t</sup> PLH		See Figures 2 and 3	–40°C to 85°C			5	μs
	Propagation delay time, high-to-low-level output	See Figures 2 and 2	25°C		2	5	μs
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	See Figures 2 and 3	–40°C to 85°C			5	
	Rise time	$V_{CC}$ slew rate $\leq 5 V/\mu s$ ,	25°C		0.4	1	
t <sub>r</sub>	Rise unie	See Figures 2 and 3	–40°C to 85°C			1	μs
4.	Fall time	See Figures 2 and 2	25°C		0.05	1	
tf	Fairume	See Figures 2 and 3	–40°C to 85°C			1	μs
• • • • •	Minimum pulse duration at $V_{CC}$ for output		25°C			5	
<sup>t</sup> w(min)	response		–40°C to 85°C			5	μs



## PARAMETER MEASUREMENT INFORMATION







NOTE A: Includes jig and probe capacitance

#### Figure 2. Test Circuit for RESET Output Switching Characteristics

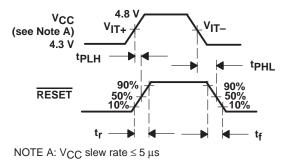


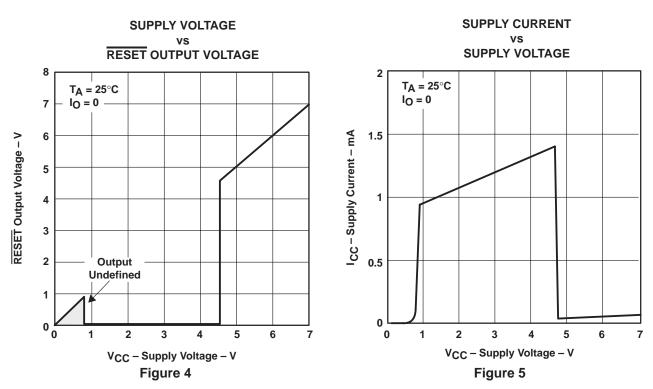
Figure 3. Switching Diagram



**TYPICAL CHARACTERISTICS<sup>†</sup>** 

		FIGURE
Vcc	Supply voltage vs RESET output voltage	4
ICC	Supply current vs Supply voltage	5
ICC	Supply current vs Free-air temperature	6
V <sub>OL</sub>	Low-level output voltage vs Low-level output current	7
VOL	Low-level output voltage vs Free-air temperature	8
IOL	Output current vs Supply voltage	9
V <sub>IT</sub>	Input threshold voltage (negative-going $V_{CC}$ ) vs Free-air temperature	10
V <sub>res</sub>	Power-up reset voltage vs Free-air temperature	11
Vres	Power-up reset voltage and supply voltage vs Time	12
	Propagation delay time	13

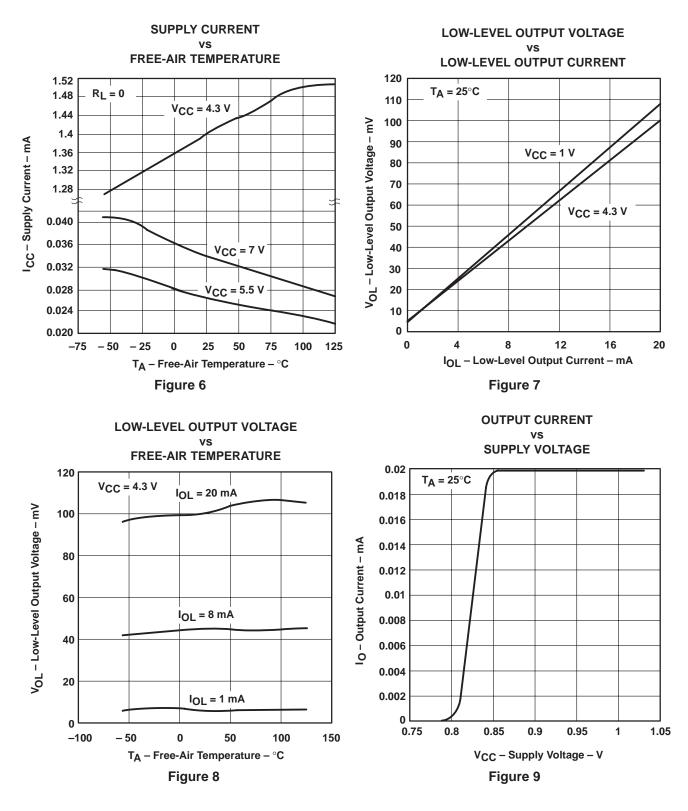
#### Table of Graphs



<sup>†</sup> Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



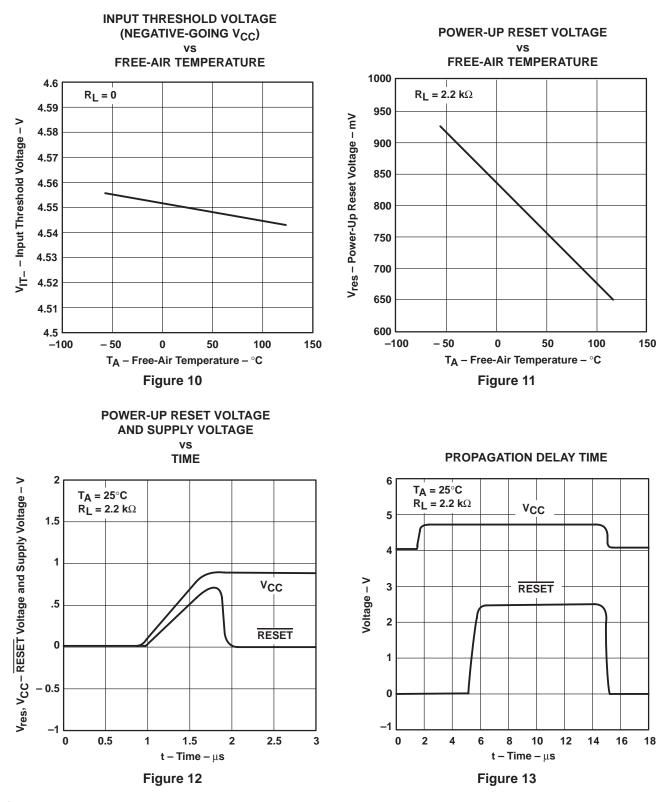
### **TYPICAL CHARACTERISTICS<sup>†</sup>**



<sup>†</sup> Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



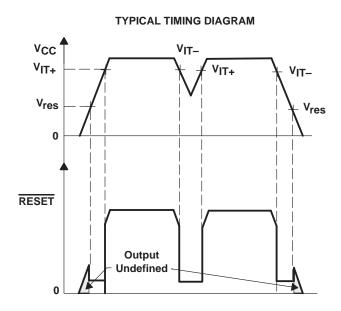
## **TYPICAL CHARACTERISTICS<sup>†</sup>**



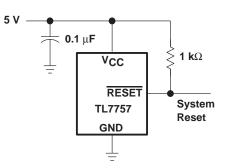
<sup>†</sup> Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



#### **APPLICATION INFORMATION**



TYPICAL APPLICATION DIAGRAM





21-Jun-2005

## **PACKAGING INFORMATION**

JMENTS

www ti com

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TL7757CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7757CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7757CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7757CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7757CLP	ACTIVE	TO-92	LP	3	1000	TBD	CU SNPB	Level-NC-NC-NC
TL7757CLPR	ACTIVE	TO-92	LP	3	2000	TBD	CU SNPB	Level-NC-NC-NC
TL7757CPK	ACTIVE	SOT-89	PK	3	1000	TBD	CU SNPB	Level-1-220C-UNLIM
TL7757ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7757IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7757IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7757IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7757ILP	ACTIVE	TO-92	LP	3	1000	TBD	CU SNPB	Level-NC-NC-NC
TL7757ILPR	ACTIVE	TO-92	LP	3	2000	TBD	CU SNPB	Level-NC-NC-NC
TL7757IPK	ACTIVE	SOT-89	PK	3	1000	TBD	CU SNPB	Level-1-220C-UNLIM
TL7757MD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7757MDR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7757MLP	OBSOLETE	TO-92	LP	3		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

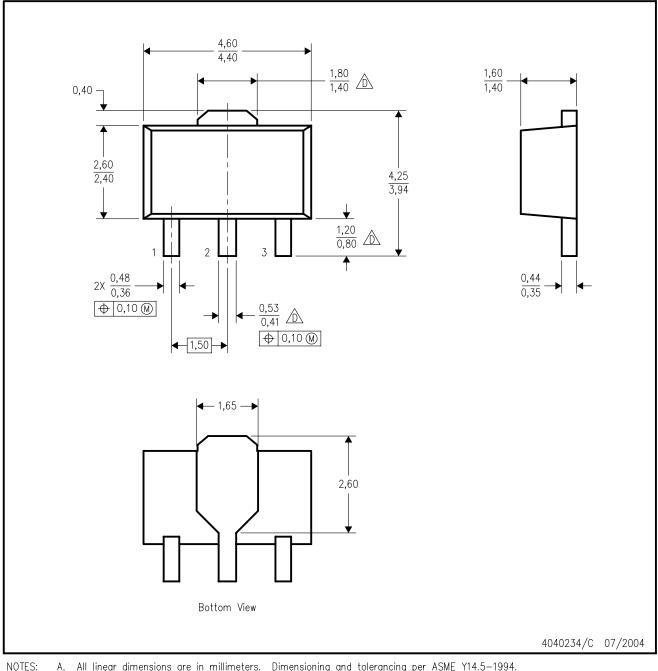
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PK (R-PSSO-F3)

PLASTIC SINGLE-IN-LINE PACKAGE



- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5-1994. Β. This drawing is subject to change without notice. C.
  - The center lead is in electrical contact with the tab.

🖄 Falls within JEDEC TO-243 variation AA, except minimum lead length, pin 2 minimum lead width, and minimum tab width.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AA.

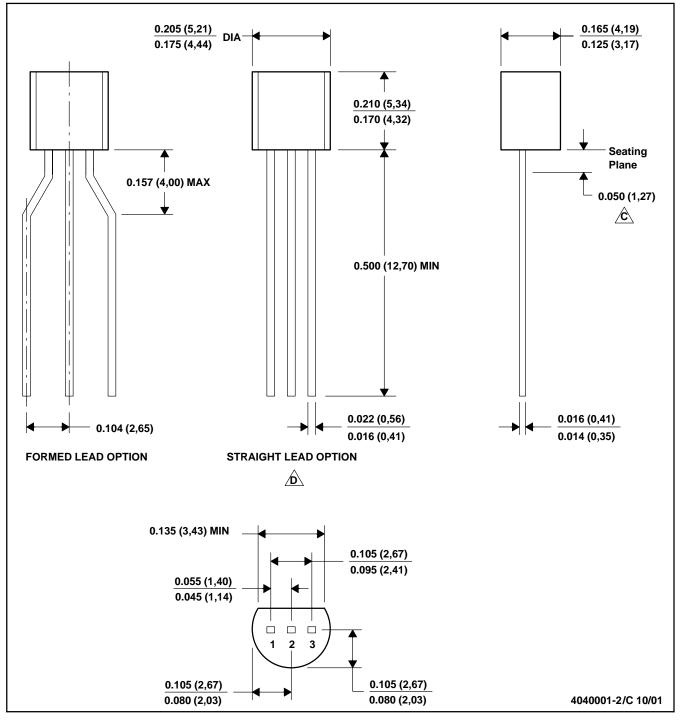


# **MECHANICAL DATA**

MSOT002A - OCTOBER 1994 - REVISED NOVEMBER 2001

#### LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

 $\underline{c}$  Lead dimensions are not controlled within this area

D. FAlls within JEDEC TO -226 Variation AA (TO-226 replaces TO-92)

E. Shipping Method:

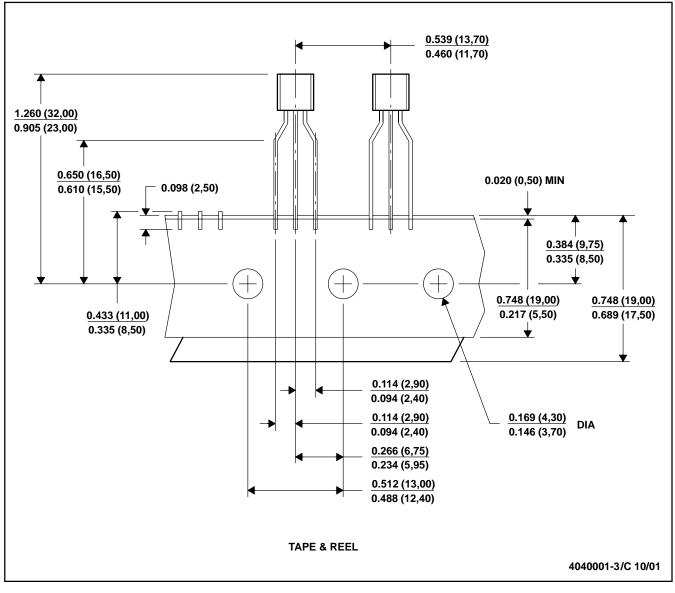
Straight lead option available in bulk pack only.

Formed lead option available in tape & reel or ammo pack.

MSOT002A - OCTOBER 1994 - REVISED NOVEMBER 2001

#### LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Tape and Reel information for the Format Lead Option package.



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